

**FH4812**
**N-Channel Double MOSFET**
**■ Description**

FH4812 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

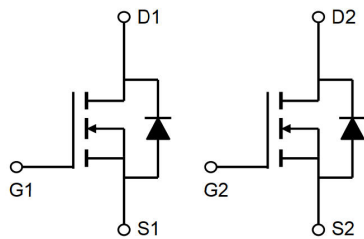
The SO-8 package is widely preferred for all commercial-industrial surface mount applications using infrared reflow technique and suited for voltage conversion or switch applications.

**■ General Features**

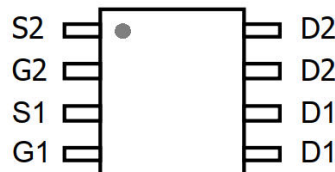
- $V_{DS} = 30V$  ,  $I_D = 10A$
- $R_{DS(ON)} < 11.5m\Omega(MAX)$  @  $V_{GS}=10V$
- $R_{DS(ON)} < 18 m\Omega(MAX)$  @  $V_{GS}=4.5V$

**■ Features**

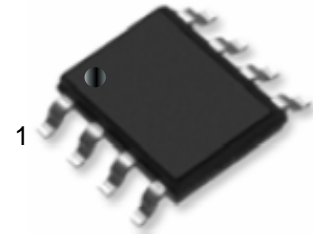
- Simple Drive Requirement
- High density cell design for ultra low Rdson
- Fast Switching Performance
- RoHS Compliant & Halogen-Free
- Fully characterized Avalanche voltage and current



Schematic diagram



Marking and pin assignment



SO-8 top view

**Absolute Maximum Ratings @ $T_j=25^\circ C$ (unless otherwise specified)**

| Symbol                 | Parameter                                  | Rating     | Units      |
|------------------------|--|------------|------------|
| $V_{DS}$               | Drain-Source Voltage                       | 30         | V          |
| $V_{GS}$               | Gate-Source Voltage                        | $\pm 20$   | V          |
| $I_D @ T_A=25^\circ C$ | Drain Current, $V_{GS} @ 10V^3$            | 10         | A          |
| $I_D @ T_A=70^\circ C$ | Drain Current, $V_{GS} @ 10V^3$            | 8.7        | A          |
| $I_{DM}$               | Pulsed Drain Current <sup>1</sup>          | 40         | A          |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation                    | 2          | W          |
| $E_{AS}$               | Single Pulse Avalanche Energy <sup>4</sup> | 7.2        | mJ         |
| $T_{STG}$              | Storage Temperature Range                  | -55 to 150 | $^\circ C$ |
| $T_J$                  | Operating Junction Temperature Range       | -55 to 150 | $^\circ C$ |

**Thermal Data**

| Symbol | Parameter   | Value | Unit         |
|--------|---|-------|--------------|
| Rthj-a | Maximum Thermal Resistance, Junction-ambient <sup>3</sup> | 62.5  | $^\circ C/W$ |

Electrical Characteristics @ $T_j=25^\circ\text{C}$  (unless otherwise specified)

| Symbol       | Parameter                                      | Test Conditions             | Min. | Typ. | Max.      | Units     |
|--------------|--|-----------------------------|------|------|-----------|-----------|
| $BV_{DSS}$   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V, I_D=250\mu A$   | 30   | -    | -         | V         |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V, I_D=10A$       | -    | -    | 11.5      | $m\Omega$ |
|              |  | $V_{GS}=4.5V, I_D=5A$       | -    | -    | 18        | $m\Omega$ |
| $V_{GS(th)}$ | Gate Threshold Voltage                         | $V_{DS}=V_{GS}, I_D=1mA$    | 1    | -    | 2         | V         |
| $g_{fs}$     | Forward Transconductance                       | $V_{DS}=5V, I_D=10A$        | -    | 40   | -         | S         |
| $I_{DSS}$    | Drain-Source Leakage Current                   | $V_{DS}=24V, V_{GS}=0V$     | -    | -    | 1         | $\mu A$   |
| $I_{GSS}$    | Gate-Source Leakage                            | $V_{GS}=\pm 20V, V_{DS}=0V$ | -    | -    | $\pm 100$ | nA        |
| $Q_g$        | Total Gate Charge                              | $I_D=5A$                    | -    | 14   | 22.4      | nC        |
| $Q_{gs}$     | Gate-Source Charge                             | $V_{DS}=15V$                | -    | 4.4  | -         | nC        |
| $Q_{gd}$     | Gate-Drain ("Miller") Charge                   | $V_{GS}=4.5V$               | -    | 5.4  | -         | nC        |
| $t_{d(on)}$  | Turn-on Delay Time                             | $V_{DS}=15V$                | -    | 9    | -         | ns        |
| $t_r$        | Rise Time                                      | $I_D=1A$                    | -    | 8    | -         | ns        |
| $t_{d(off)}$ | Turn-off Delay Time                            | $R_G=3.3\Omega$             | -    | 29   | -         | ns        |
| $t_f$        | Fall Time                                      | $V_{GS}=10V$                | -    | 9    | -         | ns        |
| $C_{iss}$    | Input Capacitance                              | $V_{GS}=0V$                 | -    | 790  | 1280      | pF        |
| $C_{oss}$    | Output Capacitance                             | $V_{DS}=15V$                | -    | 225  | -         | pF        |
| $C_{rss}$    | Reverse Transfer Capacitance                   | $f=1.0MHz$                  | -    | 160  | -         | pF        |
| $R_g$        | Gate Resistance                                | $f=1.0MHz$                  | -    | 2.5  | 5         | $\Omega$  |

## Source-Drain Diode

| Symbol   | Parameter                       | Test Conditions       | Min. | Typ. | Max. | Units |
|----------|---------------------------------|-----------------------|------|------|------|-------|
| $V_{SD}$ | Forward On Voltage <sup>2</sup> | $I_S=1.7A, V_{GS}=0V$ | -    | -    | 1.2  | V     |
| $t_{rr}$ | Reverse Recovery Time           | $I_S=10A, V_{GS}=0V,$ | -    | 11   | -    | ns    |
| $Q_{rr}$ | Reverse Recovery Charge         | $dI/dt=100A/\mu s$    | -    | 4    | -    | nC    |

## Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test
3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board,  $t \leq 10\text{sec}$ ;  $135^\circ\text{C}/W$  when mounted on Min. copper pad.
4. Starting  $T_j=25^\circ\text{C}$ ,  $V_{DD}=30V$ ,  $L=0.1mH$ ,  $R_G=25\Omega$

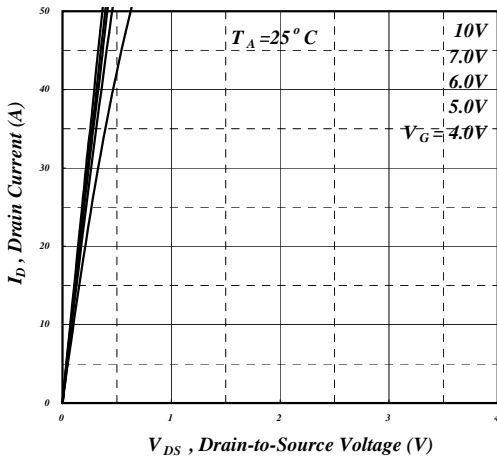


Fig 1. Typical Output Characteristics

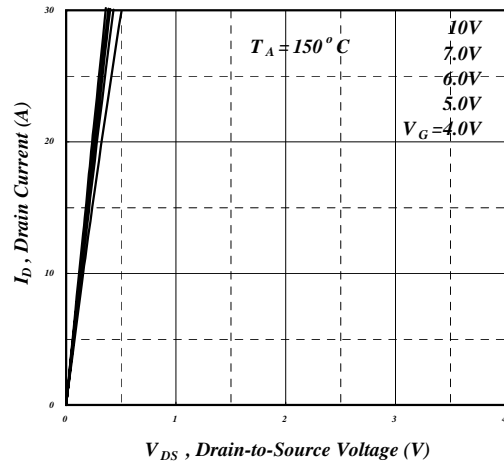


Fig 2. Typical Output Characteristics

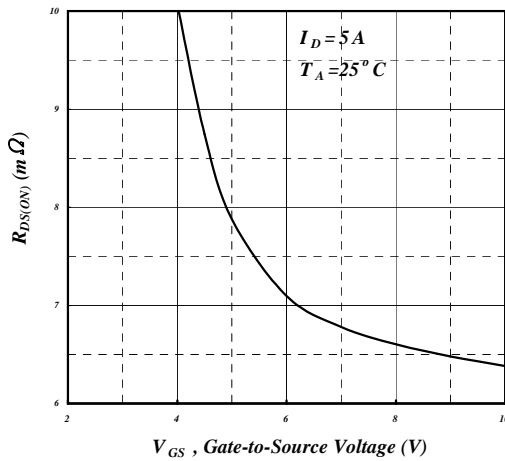


Fig 3. On-Resistance v.s. Gate Voltage

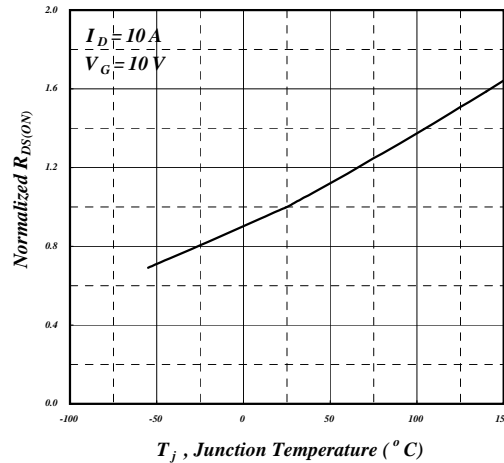


Fig 4. Normalized On-Resistance v.s. Junction Temperature

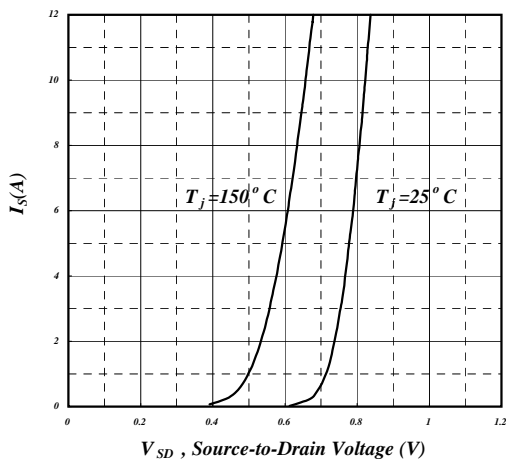


Fig 5. Forward Characteristic of Reverse Diode

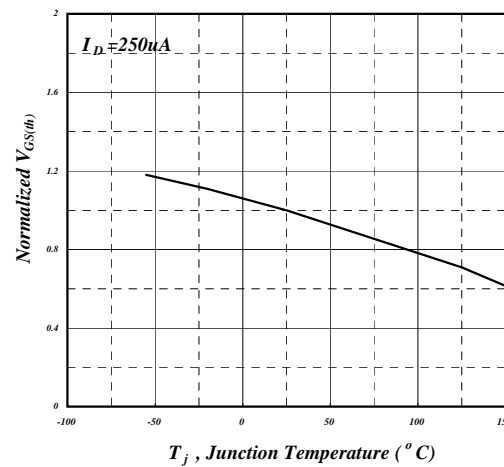


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

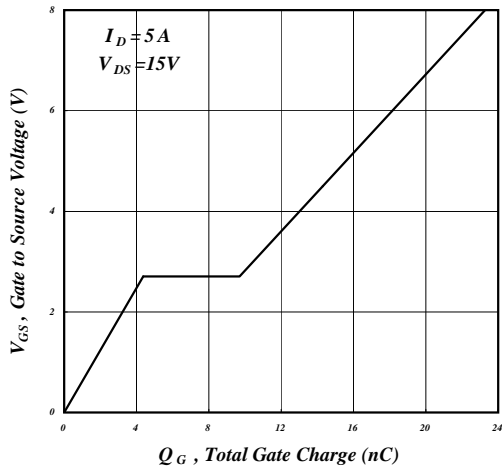


Fig 7. Gate Charge Characteristics

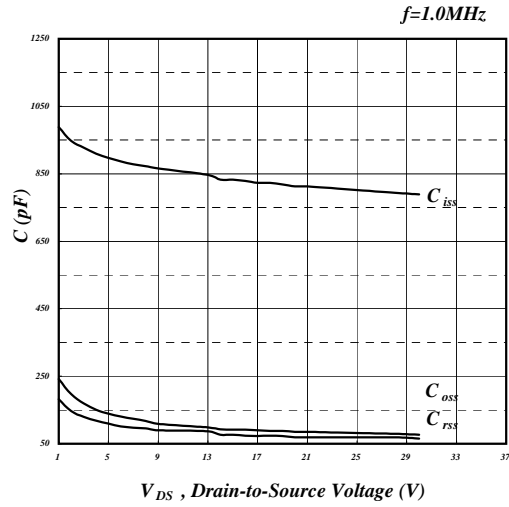


Fig 8. Typical Capacitance Characteristics

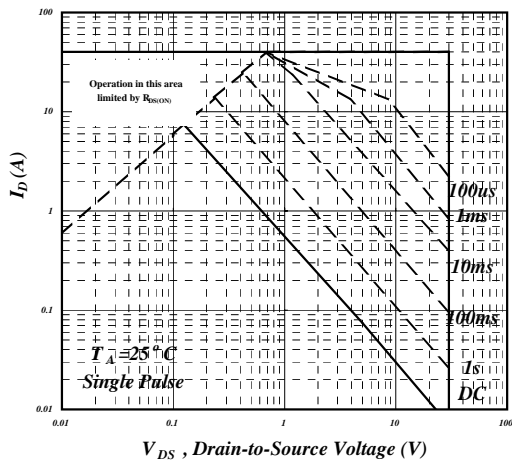


Fig 9. Maximum Safe Operating Area

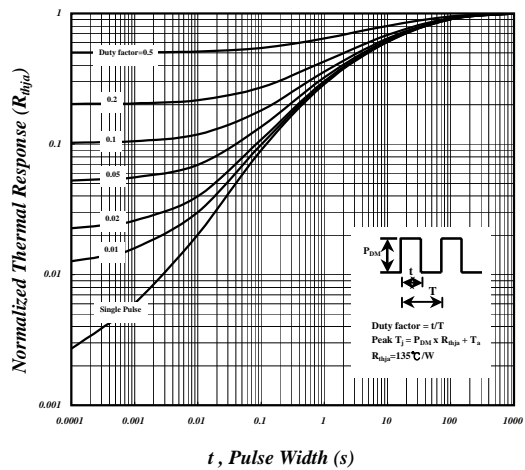


Fig 10. Effective Transient Thermal Impedance

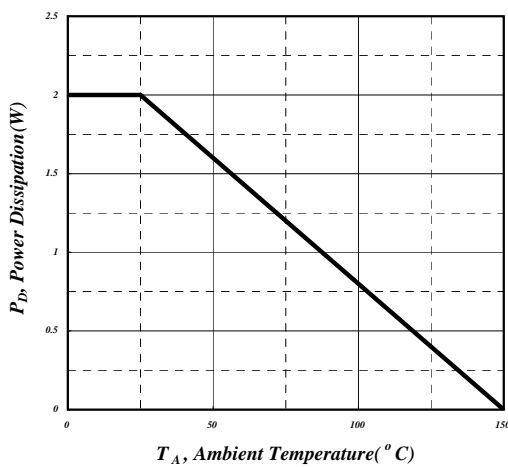


Fig 11. Total Power Dissipation

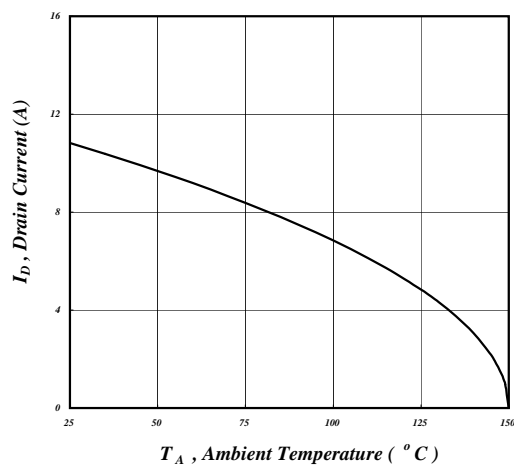
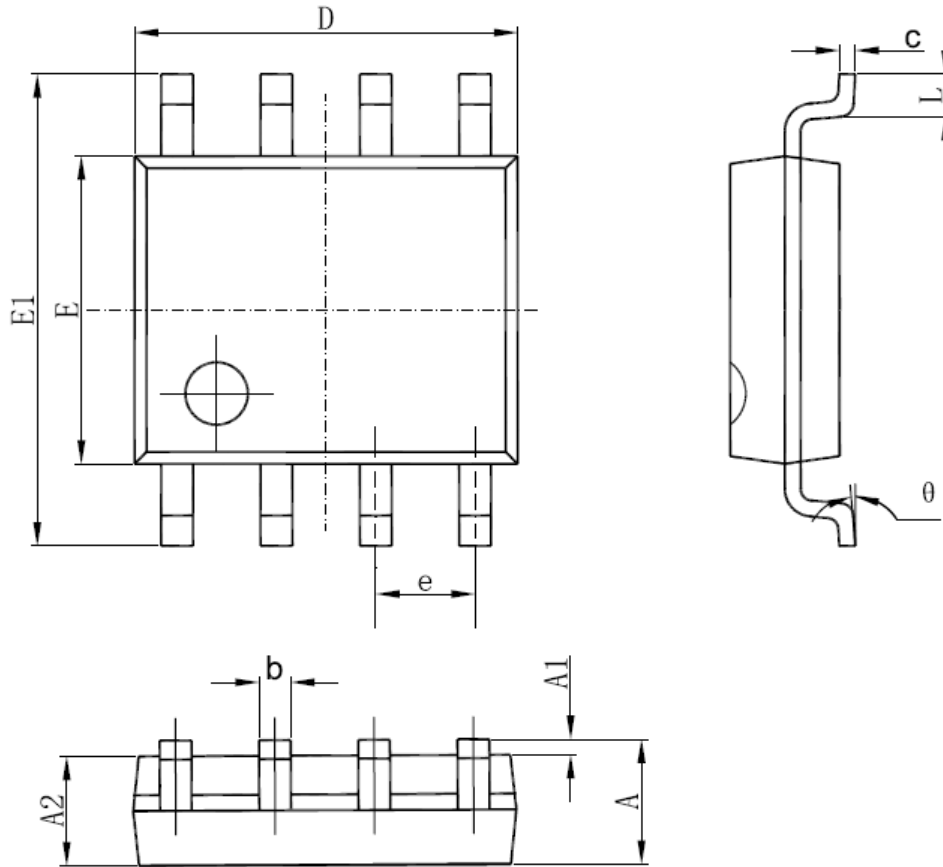


Fig 12. Drain Current v.s. Ambient Temperature

Package Information : SO-8



| SYMBOL | MM    |       | INCH  |       | SYMBOL | MM          |       | INCH        |       |
|--------|-------|-------|-------|-------|--------|-------------|-------|-------------|-------|
|        | MIN   | MAX   | MIN   | MAX   |        | MIN         | MAX   | MIN         | MAX   |
| A      | 1.350 | 1.750 | 0.053 | 0.069 | E      | 3.800       | 4.000 | 0.150       | 0.157 |
| A1     | 0.100 | 0.250 | 0.004 | 0.010 | E1     | 5.800       | 6.200 | 0.228       | 0.244 |
| A2     | 1.350 | 1.550 | 0.053 | 0.061 | e      | 1.270 (BSC) |       | 0.050 (BSC) |       |
| b      | 0.330 | 0.510 | 0.013 | 0.020 | L      | 0.400       | 1.270 | 0.016       | 0.050 |
| c      | 0.170 | 0.250 | 0.006 | 0.010 | theta  | 0°          | 8°    | 0°          | 8°    |
| D      | 4.700 | 5.100 | 0.185 | 0.200 |        |             |       |             |       |